



Material Content Data Sheet



Sales Product Name		IPD70N10S3-12		Issued		12. August 2019		
MA#		MA001913378						
Package		PG-TO252-3-11		Weight*		374.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.833	1.56	1.56	15574	15574
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		172	
	non noble metal	iron	7439-89-6	0.215	0.06		575	
wire	non noble metal	copper	7440-50-8	215.017	57.40	57.48	574087	574834
	non noble metal	aluminium	7429-90-5	5.598	1.49	1.49	14946	14946
encapsulation	organic material	carbon black	1333-86-4	1.200	0.32		3205	
	plastics	epoxy resin	-	21.004	5.61		56081	
leadfinish	inorganic material	silicondioxide	60676-86-0	97.821	26.12	32.05	261177	320463
	non noble metal	tin	7440-31-5	3.740	1.00	1.00	9986	9986
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	242	243
solder	non noble metal	tin	7440-31-5	0.095	0.03		254	
	noble metal	silver	7440-22-4	0.119	0.03		317	
heatspreader	non noble metal	lead	7439-92-1	4.537	1.21	1.27	12114	12685
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.12	5.13	51203	51269
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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